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(54) Title: CLEANING LEAD-FRAMES TO IMPROVE WIREBONDING PROCESS

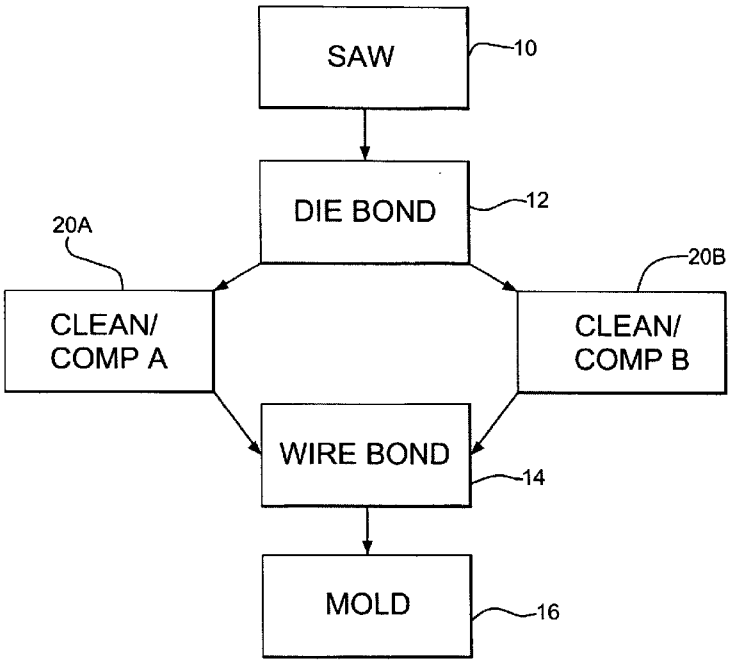


FIG. 2

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(57) Abstract: A method of processing a semiconductor substrate to remove undesired material therefrom or to prepare a surface of the semiconductor substrate for subsequent bonding wherein the substrate comprises a leadframe comprising dies, bond pads, contacts, and wires, the method comprises the step of contacting the substrate with a liquid cleaning composition and compositions useful in the method.